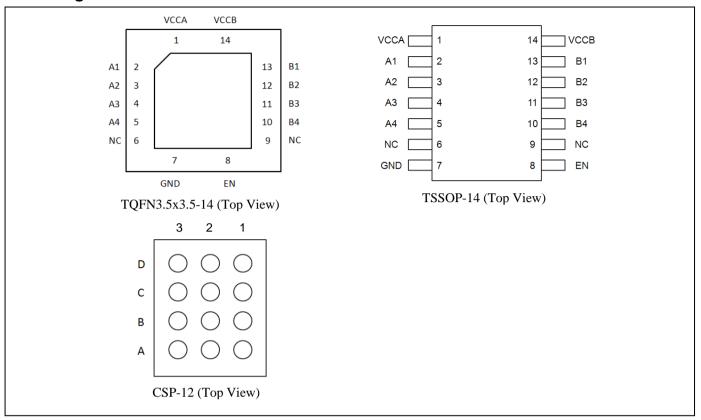




## **Pin Configuration**



## **Pin Description**

Pin No TSSOP	Pin No TQFN	Pin No CSP	Pin Name	Pin Name Type Description	
1	1	B2	V <sub>CCA</sub> Power		A port supply voltage. $1.1 \text{V} \leq \text{V}_{\text{CCA}} \leq 3.6 \text{ V}$
2	2	A3	A1	I/O	Input/output A1. Referenced to V <sub>CCA</sub> .
3	3	В3	A2	I/O	Input/output A2. Referenced to V <sub>CCA</sub>
4	4	C3	A3	I/O	Input/output A3. Referenced to V <sub>CCA</sub>
5	5	D3	A4	I/O	Input/output A4. Referenced to V <sub>CCA</sub>
7	7	D2	GND	GND GND Ground.	
8	8	C2	EN	Output enable (active High)	
10	10	D1	B4	I/O	Input/output B4. Referenced to V <sub>CCB</sub>
11	11	C1	В3	I/O	Input/output B3. Referenced to V <sub>CCB</sub>
12	12	B1	B2	I/O	Input/output B2. Referenced to V <sub>CCB</sub>
13	13	A1	B1	I/O	Input/output B1. Referenced to V <sub>CCB</sub>
14	14	A2	V <sub>CCB</sub>	Power	B port supply voltage. 1.1 V $\leq$ V <sub>CCB</sub> $\leq$ 3.6V
6, 9	6, 9	/	NC	NC	Not Connect







## **Maximum Ratings**

Storage Temperature	65°C to +150°C
DC Supply Voltage Port B	0.3V to +5.5V
DC Supply Voltage Port A	0.3V to+5.5V
Vi(A) referenced DC Input / Output Voltage	0.3V to +5.5V
Vi(B) referenced DC Input / Output Voltage	0.3V to+5.5V
Enable Control Pin DC Input Voltage	0.3V to+5.5V
Short Circuit duration (I/O to GND)	40mA

#### Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**Recommended Operation Conditions** 

Symbol	Parameter		Тур	Max	Unit
$V_{CCA}$	V <sub>CCA</sub> Positive DC Supply Voltage		-	3.6	V
$V_{CCB}$	V <sub>CCB</sub> Positive DC Supply Voltage		-	3.6	V
$V_{EN}$	Enable Control Pin Voltage	0	-	3.6	V
$V_{IO}$	I/O Pin Voltage		-	3.6	V
$\Delta t / \Delta V$	Input Transition Rise or Fall Time	-	-	10	ns/V
$T_A$	Operating Temperature Range	-40	-	+85	°C

#### **DC Electrical Characteristics**

Unless otherwise specified, -40°C $\leq$ T<sub>A</sub> $\leq$ 85°C, 1.1V $\leq$ Vcc $\leq$ 3.6V

Symbol	Parameter	Test Conditions		Min	Тур	Max	Unit
		$2.3V \le V_{CC(B)} \le$	≤3.6V	$V_{CCB} - 0.4$	-	-	V
$V_{IHB}$	B port Input HIGH Voltage	$1.5V \le V_{CC(B)} \le$	<2.3V	$V_{\rm CCB} - 0.2$			V
		$1.1V \le V_{CC(B)} \le$	<1.5V	$V_{CCB}-0.1$			V
$V_{\rm ILB}$	B port Input LOW Voltage				-	0.15	V
		$2.3V \le V_{CC(A)} \le$	≤3.6V	$V_{CCA}$ – 0.4			V
$V_{IHA}$	A port Input HIGH Voltage	$1.5V \le V_{CC(A)} \le$	<2.3V	$V_{CCA}$ – 0.2			V
		$1.1V \le V_{CC(A)} \le$	<1.5V	$V_{CCA} - 0.1$			V
$V_{ILA}$	A port Input LOW Voltage	-		-	-	0.15	V
V	Control Pin Input HIGH Voltage	$1.5V < V_{CC(A)}$	≤3.6V	$0.65*V_{CCA}$	-	-	V
V <sub>IH(EN)</sub>	Control Fill Input HIGH Voltage	$1.1V \le V_{CC(A)} \le$	≤1.5V	$0.6*V_{CCA}$			V
		$1.5V < V_{CC(A)}$	≤3.6V	-	-	0.35* V <sub>CCA</sub>	V
$V_{\rm IL(EN)}$	Control Pin Input LOW Voltage	$1.1V \le V_{CC(A)} \le$	≤1.5V			0.2* V <sub>CCA</sub>	V
$V_{OHB}$	B port Output HIGH Voltage	B port source current = -20 μA		$0.8*V_{CCB}$	-	-	V
$V_{OLB}$	B port Output LOW Voltage	B port sink cu	rrent =1 mA	-	-	0.4	V
$V_{OHA}$	A port Output HIGH Voltage	A port source	current= -20 μA	0.8* V <sub>CCA</sub>	-	-	V
$V_{OLA}$	A port Output LOW Voltage	A port sink cu	irrent =1 mA	-	-	0.4	V
			$f_{CC(A)}=1.1V$ to 3.6V, $f_{CC(B)}=1.1V$ to 3.6V	-	1.0	3	μΑ
,	W. Garata Carrent	$I_0 = 0A;$ V	$V_{CC(A)}=1.1V, V_{CC(B)}=1.8V$	_	0.6	2	μΑ
$I_{CCB}$	V <sub>CCB</sub> Supply Current		$V_{CC(A)}=1.8V, V_{CC(B)}=3.3V$	-	0.7	2	μΑ
		or High V	$V_{CC(A)} = 3.6V, V_{CC(B)} = 0V$	_		1	μΑ
		V	$V_{CC(A)} = 0V, V_{CC(B)} = 3.6V$	_		1	μΑ
_	V <sub>CCA</sub> Supply Current		$f_{CC(A)}=1.1V$ to 3.6V, $f_{CC(B)}=1.1V$ to 3.6V	-	0.2	1	μΑ
$I_{CCA}$			$V_{CC(A)} = 3.6V, V_{CC(B)} = 0V$	-	-	1	μΑ
		or High V	$V_{CC(A)} = 0V, V_{CC(B)} = 3.6V$	-	-	1	μA







Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
I <sub>OZ</sub>	I/O Tri-state Output Mode Leakage Current	-	-	0.1	1.0	μΑ
$I_{I-EN}$	Control pin leakage Current	$V_{I}=V_{CCI}$ or GND	-	-	1	μA
$R_{PU}$	Pull-Up Resistors I/O A and B	-	-	10	-	kΩ
$C_{i}$	EN	$V_{CC(A)} = 3.3V, V_{CC(B)} = 3.3V$	-	-	0.5	pF
$C_{iO}$	A port	$V_{CC(A)} = 3.3V, V_{CC(B)} = 3.3V$	-	-	5	pF
	B port	$V_{CC(A)} = 3.3V, V_{CC(B)} = 3.3V$	-	-	5	pF

Note: All units are production tested at  $T_A = +25$  °C. Limits over the operating temperature range are guaranteed by design. Typical values are for  $V_{CCB} = +2.8$  V,  $V_{CCA} = +1.8$  V and  $T_A = +25$  °C.

#### **AC Electrical Characteristics**

Timing Characteristics – Rail-to-Rail Driving Configuration (I/O test circuits of Figures 2, 3 and 7,  $C_{LOAD} = 15$  pF, driver output impedance  $\leq 50\Omega$ ,  $R_{LOAD} = 1$  M $\Omega$ ,  $T_A = -40$ °C to 85°C, unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$V_{CCA} = 1.2$	$2V \pm 0.1V$ , $V_{CCB} = 1.8V \pm 0.15V$					
$t_{RB}$	B port Rise Time	-			20	nS
$t_{FB}$	B port Fall Time	-			25	nS
$t_{RA}$	A port Rise Time	-			20	nS
$t_{\rm FA}$	A port Fall Time	-			20	nS
$t_{\rm EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			200	nS
$t_{\mathrm{PHL-A-B}}$	Propagation Delay	-			9	nS
$t_{\rm PLH-A-B}$	(Driving A)	-			11	nS
$t_{PHL-B-A}$	Propagation Delay	-			9	nS
$t_{\rm PLH-B-A}$	(Driving B)	-			10	nS
t <sub>PPSKEW</sub>	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
$V_{CCA} = 1.2$	$2V \pm 0.1V$ , $V_{CCB} = 2.5V \pm 0.2V$					
t <sub>RB</sub>	B port Rise Time	-			12	nS
$t_{FB}$	B port Fall Time	-			14	nS
$t_{RA}$	A port Rise Time	-			20	nS
$t_{FA}$	A port Fall Time	-			25	nS
$t_{\rm EN}$	Enable Time	-			200	nS
t <sub>DIS</sub>	Disable Time	-			200	nS
$t_{PHL-A-B}$	Propagation Delay	-			9	nS
$t_{PLH-A-B}$	(Driving A)	-			11	nS
t <sub>PHL-B-A</sub>	Propagation Delay	-			9	nS
t <sub>PLH-B-A</sub>	(Driving B)	-			10	nS
t <sub>PPSKEW</sub>	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
$V_{CCA} = 1.2$	$2V \pm 0.1V$ , $V_{CCB} = 3.3V \pm 0.3V$					
t <sub>RB</sub>	B port Rise Time	-			12	nS
t <sub>FB</sub>	B port Fall Time	-			18	nS
$t_{RA}$	A port Rise Time	-			16	nS
$t_{FA}$	A port Fall Time	-			30	nS
$t_{EN}$	Enable Time	-			200	nS
t <sub>DIS</sub>	Disable Time	-			200	nS
$t_{\mathrm{PHL-A-B}}$	Propagation Delay	-			8	nS
$t_{PLH-A-B}$	(Driving A)	-			11	nS



Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
$t_{PHL-B-A}$	Propagation Delay	-			8	nS
$t_{\rm PLH-B-A}$	(Driving B)	-			10	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
$V_{CCA} = 1.8V$	$V \pm 0.15 V$ , $V_{CCB} = 1.2 V \pm 0.1 V$					
$t_{RB}$	B port Rise Time	-			25	nS
$t_{FB}$	B port Fall Time	-			25	nS
$t_{RA}$	A port Rise Time	-			14	nS
$t_{FA}$	A port Fall Time	-			25	nS
$t_{EN}$	Enable Time	-			200	nS
t <sub>DIS</sub>	Disable Time	-			200	nS
t <sub>PHL-A-B</sub>	Propagation Delay	-			10	nS
t <sub>PLH-A-B</sub>	(Driving A)	-			15	nS
t <sub>PHL-B-A</sub>	Propagation Delay	-			12	nS
t <sub>PLH-B-A</sub>	(Driving B)	-			12	nS
t <sub>PPSKEW</sub>	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
$V_{CCA} = 1.8$	$8V \pm 0.15V$ , $V_{CCB} = 2.5V \pm 0.2V$	•	•	•	•	
t <sub>RB</sub>	B port Rise Time	-			8	nS
$t_{FB}$	B port Fall Time	-			8	nS
$t_{RA}$	A port Rise Time	-			6	nS
$t_{FA}$	A port Fall Time	-			12	nS
$t_{\rm EN}$	Enable Time	-			200	nS
t <sub>DIS</sub>	Disable Time	-			150	nS
t <sub>PHL-A-B</sub>	Propagation Delay	-			5	nS
t <sub>PLH-A-B</sub>	(Driving A)	-			4	nS
t <sub>PHL-B-A</sub>	Propagation Delay	-			4	nS
t <sub>PLH-B-A</sub>	(Driving B)	-			4	nS
t <sub>PPSKEW</sub>	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps
$V_{CCA} = 1.8$	$3V \pm 0.15V$ , $V_{CCB} = 3.3V \pm 0.3V$					
$t_{RB}$	B port Rise Time	-			8	nS
$t_{FB}$	B port Fall Time	-			8	nS
t <sub>RA</sub>	A port Rise Time	-			4	nS
$t_{FA}$	A port Fall Time	-			10	nS
$t_{\rm EN}$	Enable Time	-			180	nS
t <sub>DIS</sub>	Disable Time	-			120	nS
t <sub>PHL-A-B</sub>	Propagation Delay	-			6	nS
t <sub>PLH-A-B</sub>	(Driving A)	-			4	nS
t <sub>PHL-B-A</sub>	Propagation Delay	-			4	nS
t <sub>PLH-B-A</sub>	(Driving B)	-			4	nS
t <sub>PPSKEW</sub>	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps



Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
$V_{CCA} = 2.5$	$V \pm 0.2V$ , $V_{CCB} = 1.2V \pm 0.1V$	·				
t <sub>RB</sub>	B port Rise Time	-			25	nS
$t_{FB}$	B port Fall Time	-			30	nS
$t_{RA}$	A port Rise Time	-			12	nS
$t_{FA}$	A port Fall Time	-			30	nS
$t_{EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			180	nS
$t_{PHL-A-B}$	Propagation Delay	_			10	nS
$t_{PLH-A-B}$	(Driving A)	-			14	nS
$t_{PHL-B-A}$	Propagation Delay	-			20	nS
$t_{PLH-B-A}$	(Driving B)	-			12	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
$V_{CCA} = 2.$	$5V\pm0.2V, V_{CCB} = 1.8V\pm0.15V$				_	
$t_{RB}$	B port Rise Time	-			8	nS
$t_{FB}$	B port Fall Time	-			9	nS
$t_{RA}$	A port Rise Time	-			9	nS
$t_{FA}$	A port Fall Time	-			9	nS
$t_{EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			120	nS
$t_{PHL-A-B}$	Propagation Delay	_			3	nS
$t_{PLH-A-B} \\$	(Driving A)	-			2	nS
$t_{PHL-B-A}$	Propagation Delay	-			5	nS
$t_{PLH-B-A} \\$	(Driving B)	-			5	nS
$t_{PPSKEW}$	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps
$V_{CCA} = 2$	$2.5V \pm 0.2V, V_{CCB} = 3.3V \pm 0.3V$				•	ī
$t_{RB}$	B port Rise Time	-			7	nS
$t_{FB}$	B port Fall Time	-			8	nS
$t_{RA}$	A port Rise Time	-			4	nS
$t_{FA}$	A port Fall Time	-			10	nS
$t_{\rm EN}$	Enable Time	-			200	nS
$t_{DIS}$	Disable Time	-			120	nS
t <sub>PHL-A-B</sub>	Propagation Delay	-			3	nS
t <sub>PLH-A-B</sub>	(Driving A)	-			5	nS
t <sub>PHL-B-A</sub>	Propagation Delay	-			4	nS
t <sub>PLH</sub> -B-A	(Driving B)	-			4	nS
t <sub>PPSKEW</sub>	Part-to-Part Skew				1	nS
MDR	Maximum Data Rate	<u>F</u>			24	Mbps
	$3V \pm 0.3V$ , $V_{CCB} = 1.2V \pm 0.1V$		<u> </u>		0.5	- 0
t <sub>RB</sub>	B port Rise Time	<del> </del>			26	nS
t <sub>FB</sub>	B port Fall Time	<del> </del>			32	nS
t <sub>RA</sub>	A port Rise Time	<del>-</del>			12	nS
t <sub>FA</sub>	A port Fall Time	<del> </del>			40	nS
t <sub>EN</sub>	Enable Time	<del> </del>			120	nS
t <sub>DIS</sub>	Disable Time	<del>-</del>			300	nS
$t_{PHL-A-B}$	Propagation Delay	-			10	nS





Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
t <sub>PLH-A-B</sub>	(Driving A)	-			14	nS
t <sub>PHL-B-A</sub>	Propagation Delay	-			25	nS
t <sub>PLH-B-A</sub>	(Driving B)	-			12	nS
t <sub>PPSKEW</sub>	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			20	Mbps
$V_{CCA} = 3$ .	$3V\pm0.3V$ , $V_{CCB} = 1.8V\pm0.15V$					
t <sub>RB</sub>	B port Rise Time	-			6	nS
$t_{FB}$	B port Fall Time	-			11	nS
$t_{RA}$	A port Rise Time	-			6	nS
$t_{FA}$	A port Fall Time	-			7	nS
$t_{EN}$	Enable Time	-			120	nS
$t_{DIS}$	Disable Time	-			200	nS
$t_{PHL-A-B}$	Propagation Delay	-			4	nS
$t_{PLH-A-B}$	(Driving A)	-			4	nS
t <sub>PHL-B-A</sub>	Propagation Delay	-			5	nS
t <sub>PLH-B-A</sub>	(Driving B)	-			5	nS
t <sub>PPSKEW</sub>	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps
$V_{CCA} = 3$ .	$3V\pm0.3V$ , $V_{CCB} = 2.5V\pm0.2V$					
$t_{RB}$	B port Rise Time	-			6	nS
$t_{FB}$	B port Fall Time	-			10	nS
$t_{RA}$	A port Rise Time	-			6	nS
$t_{FA}$	A port Fall Time	-			7	nS
$t_{EN}$	Enable Time	-			120	nS
$t_{DIS}$	Disable Time	-			200	nS
$t_{PHL-A-B}$	Propagation Delay	-			4	nS
t <sub>PLH-A-B</sub>	(Driving A)	-			4	nS
$t_{PHL-B-A}$	Propagation Delay	-			4	nS
t <sub>PLH-B-A</sub>	(Driving B)	-			4	nS
t <sub>PPSKEW</sub>	Part-to-Part Skew	-			1	nS
MDR	Maximum Data Rate	-			24	Mbps

# Timing Characteristics – Open Drain Driving Configuration $(1.1 \le V_{CCA} \le V_{CCB} \le 3.6 V, \, T_A = -40\,^{\circ}C \text{ to } 85\,^{\circ}C)$

Symbol	Parameter	<b>Test Conditions</b>	Min	Тур	Max	Unit
t <sub>RB</sub>	B port Rise Time	-	-	-	300	nS
$t_{FB}$	B port Fall Time	-	-	-	30	nS
$t_{RA}$	A port Rise Time	ı	-	-	300	nS
$t_{FA}$	A port Fall Time	-	-	-	30	nS
t <sub>PHL-A-B</sub>	Propagation Delay	-	-	-	20	nS
t <sub>PLH-A-B</sub>		ı	-	-	260	nS
t <sub>PHL-B-A</sub>	Propagation Delay	ı	-	-	20	nS
$t_{PLH-B-A}$	Propagation Delay (Driving B)	-	-	-	260	nS
t <sub>PPSKEW</sub>	Part-to-Part Skew	<del>-</del>	_	-	1	nS
MDR	Maximum Data Rate	<del>-</del>	2	-	-	Mbps



### **Test Circuits**

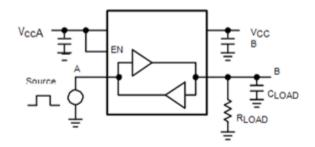


Figure 2.Rail-to-Rail Driving A

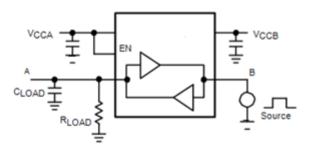


Figure 3. Rail-to-Rail Driving B

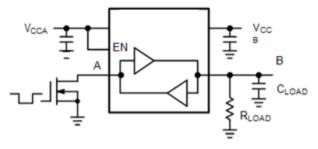


Figure 4. Open-Drain Driving A

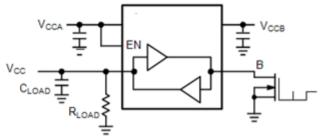
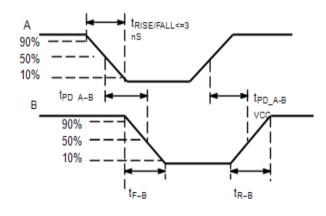
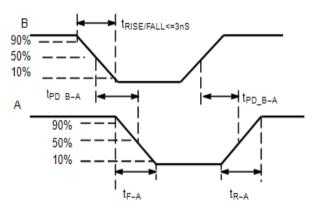


Figure 5. Open-Drain Driving B



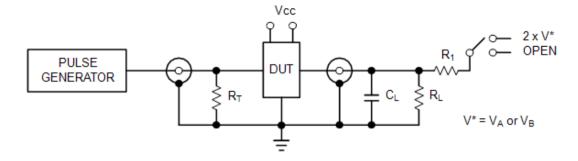


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Figure 6. Definition of Timing Specification Parameters





++	Test	Switch
	t <sub>PZH</sub> , t <sub>PHZ</sub>	Open
	t <sub>PZL</sub> , t <sub>PLZ</sub>	2 x V*

C<sub>L</sub> = 15 pF or equivalent (Includes jig and probe capacitance)

 $R_L = R_1 = 50 \text{ k} \Omega$  or equivalent

 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ ) V\* = V<sub>A</sub>or V<sub>B</sub> for A or B measurements,

respectively.

Figure 7. Test Circuit for Enable/Disable Time Measurement

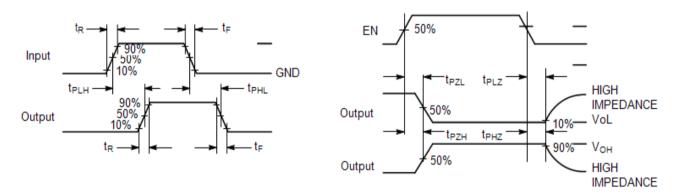


Figure 8. Timing Definitions for Propagation Delays and Enable/Disable Measurement

#### **Functional Description**

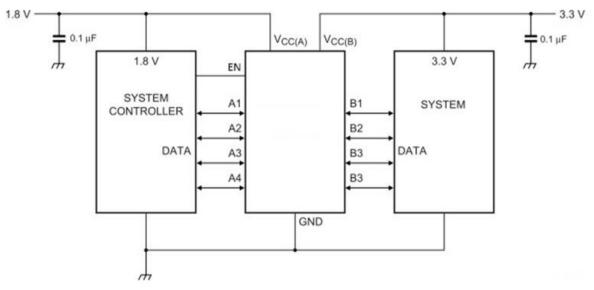
The PI4ULS3V204 is a 4-bit configurable dual-supply bidirectional auto sensing translator that does not require a directional control pin. The A and B ports are designed to track two different power supply rails,  $V_{CCA}$  and  $V_{CCB}$  respectively. Both the V<sub>CCA</sub> and V<sub>CCB</sub> supply rails are configurable from 1.1 V to 3.6V. This allows voltage logic signals on the V<sub>CCA</sub> side to be translated into lower, higher or equal value voltage logic signals on the V<sub>CCB</sub> side, and vice—versa.

The translator has integrated 10 k $\Omega$  pull-up resistors on the I/O lines. The integrated pull-up resistors are used to pull-up the I/O lines to either V<sub>CCA</sub> or V<sub>CCB</sub>. The PI4ULS3V2O4 is an excellent match for open-drain applications such as the I<sup>2</sup>C communication bus.



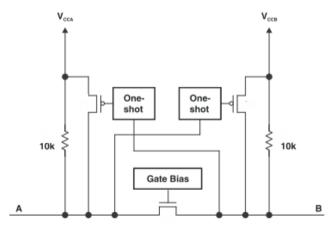


## **Application Information**



#### **Level Translator Architecture**

The PI4ULS3V204 auto sense translator provides bidirectional voltage level shifting to transfer data in multiple supply voltage systems. This device has two supply voltages,  $V_{CCA}$  and  $V_{CCB}$ , which set the logic levels on the input and output sides of the translator. When used to transfer data from A port to B port, input signals referenced to the  $V_{CCA}$  supply are translated to output signals with a logic level matched to  $V_{CCB}$ . In a similar manner, translation shifts input signals with a logic level compatible to  $V_{CCB}$  to an output signal matched to  $V_{CCA}$ . The PI4ULS3V204 consists of two bidirectional channels that independently determine the direction of the data flow without requiring a directional pin. The one-shot circuits are used to detect the rising or falling input signals. In addition, the one shots decrease the rise and fall time of the output signal for high-to-low and low-to-high transitions. Each input/output channel has an internal  $10~k\Omega$  pull-up resistors. The magnitude of the pull-up resistors can be reduced by connecting external resistors in parallel to the internal  $10~k\Omega$  resistors.



#### **Input Driver Requirements**

The rise (tR) and fall (tF) timing parameters of the open drain outputs depend on the magnitude of the pull—up resistors. In-addition, the propagation times (tPD), skew (tPSKEW) and maximum data rate depend on the impedance of the device that is connected to the translator. The timing parameters listed in the data sheet assume that the output impedance of the drivers connected to the translator is less than  $50 \text{ k}\Omega$ .





## Enable Input (EN)

The PI4ULS3V204 has an Enable pin (EN) that provides tri-state operation at the I/O pins. Driving the Enable pin to a low logic level minimizes the power consumption of the device and drives the I/O  $V_{CCB}$  and I/O  $V_{CCA}$  pins to a high impedance state. Normal translation operation occurs when the EN pin is equal to a logic high signal. The EN pin is referenced to the  $V_{CCA}$  supply and has overvoltage tolerant protection.

### **Power Supply Guidelines**

During normal operation, supply voltage  $V_{\text{CCA}}$  can be greater than, less than or equal to  $V_{\text{CCB}}$ . The sequencing of the power supplies will not damage the device during the power up operation. For optimal performance,  $0.01\mu\text{F}$  to  $0.1\mu\text{F}$  decoupling capacitors should be used on the  $V_{\text{CCA}}$  and  $V_{\text{CCB}}$  power supply pins. Ceramic capacitors are a good design choice to filter and bypass any noise signals on the voltage lines to the ground plane of the PCB. The noise immunity will be maximized by placing the capacitors as close as possible to the supply and ground pins, along with minimizing the PCB connection traces.

## **Part Marking**

**ZB** Package

PI4ULS 3V204ZBE ZYYWWJG

Z: Die Rev

YYWW: Date Code (Year & Workweek)

J: Assembly Site Code G: Wafer Fab Site Code

#### **GA Package**

PI4ULS 3V204GAE ZYYWWXX

Z: Die Rev YY: Year

WW: Workweek
1st X: Assembly Code
2nd X: Fab Code

L Package

PI4ULS 3V204LE ZABGG

Z: Die Rev

AB: Date Code (Year & Workweek)

G: Assembly Site Code G: Wafer Fab Site Code

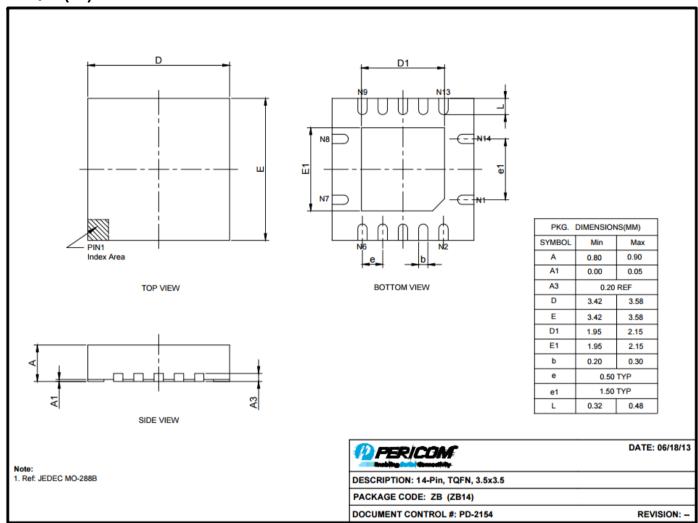
The Bar above 2nd "G" means Cu wire

Downloaded from Arrow.com.





# Packaging Mechanical: 14-TQFN (ZB)

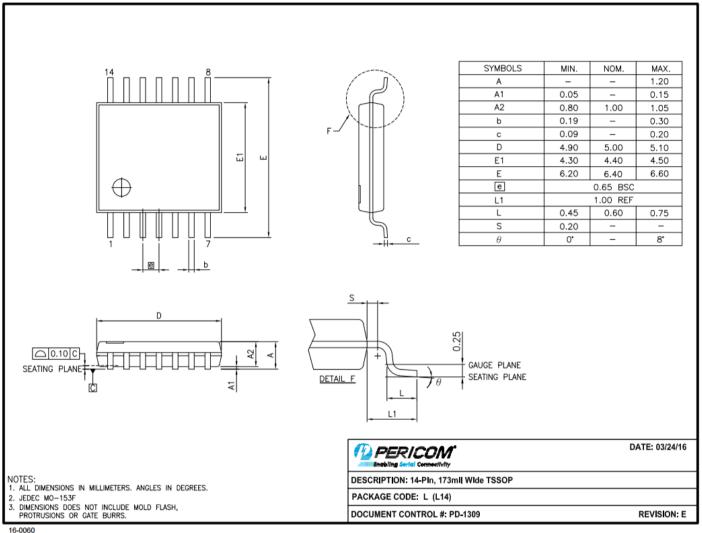


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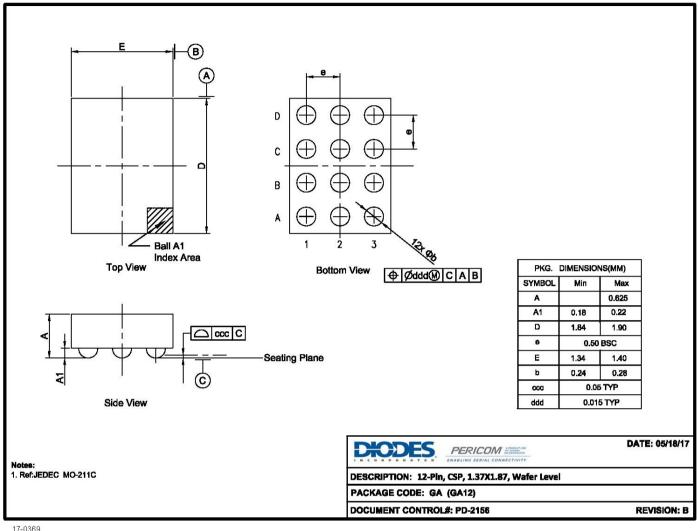
## 14-TSSOP (L)







#### 12-CSP (GA)



17-0369

#### For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

## **Ordering Information**

Part Number	Package Code	Package Description
PI4ULS3V204LEX	L	14-Pin,173 mil Wide (TSSOP)
PI4ULS3V204ZBEX	ZB	14-Pin, 3.5x3.5 (TQFN)
PI4ULS3V204GAEX	GA	12-Pin, 1.37x1.87, Wafer Level (CSP)
PI4ULS3V204ZBEX-13R	ZB	14-Pin, 3.5x3.5 (TQFN), Pin 1 orientation is Top Left

#### Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. E = Pb-free and Green
- $_{5.}$  X suffix = Tape/Reel
- 6. For packaging detail, go to our website at: https://www.diodes.com/assets/MediaList-Attachments/Diodes-Package-Information.pdf





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